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LM2422TE 220V Monolithic Triple Channel 30 MHz CRT DTV Driver

Check for Samples: LM2422TE

FEATURES

- 30 MHz Bandwidth
- **Current Output for IK Feedback Systems**
- Greater than 130V_{P-P} Output Swing Capability
- 0V to 5V input voltage range
- Stable with 0 pF-20 pF Capacitive Loads and **Inductive Peaking Networks**
- Convenient TO-220 Staggered Thin Lead Package Style

APPLICATIONS

DC Coupled HDTV Applications Using the 1080i Format as well as Other DTV and Standard TV Formats.

Connection Diagram

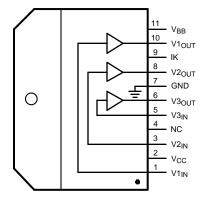


Figure 1. Top View See Package Number TO-220

DESCRIPTION

The LM2422 is a triple channel high voltage CRT driver circuit designed for use in DTV applications. The IC contains three high input impedance, wide band amplifiers which directly drive the RGB cathodes of a CRT. Each channel has its gain internally set to -52 and can drive CRT capacitive loads as well as resistive loads present in other applications, limited only by the package's power dissipation.

The IC is packaged in an industry standard 11-lead TO-220 molded plastic power package designed to meet high voltage spacing requirements. See THERMAL CONSIDERATIONS section.

Schematic Diagram

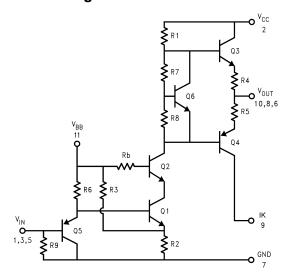


Figure 2. Simplified Schematic Diagram (One Channel)



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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TEXAS INSTRUMENTS

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ABSOLUTE MAXIMUM RATINGS(1)(2)(3)

Supply Voltage (V _{CC})		+250V
Bias Voltage (V _{BB})		+16V
Input Voltage (V _{IN})		−0.5V to V _{BB} +0.5V
Storage Temperature Range (T _{STG})		−65°C to +150°C
Lead Temperature (Soldering, <10 sec.)		300°C
ESD Tolerance,	Human Body Model	2 kV
	Machine Model	200V
Junction Temperature		150°C
θ_{JC} (typ)		1.8°C/W

- (1) All voltages are measured with respect to GND, unless otherwise specified.
- (2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.

OPERATING RATINGS(1)

V _{CC}	+100V to +230V			
V_{BB}	+7V to +13V			
V _{IN}	+0V to +5V			
V _{OUT}	+40V to +215V			
Case Temperature (22W max power)	110°C			
Do not operate the part without a heat sink. Heat sink must have a thermal resistance under 2.3°C/W. (2)				

- (1) Operating ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. Datasheet min/max specification limits are specified by design, test, or statistical analysis. The ensured specifications apply only for the test conditions listed. Some performance characteristics may change when the device is not operated under the listed test conditions.
- (2) Running the 1 MHz to 30 MHz test pattern at 1080i this part will dissipate approximately 22 W. This is the commonly accepted test pattern that is representative of the worst case high frequency content for normal television viewing. This is the pattern used to estimate the worst case power dissipation of the LM2422 in its normal application. It is recommended to use a heat sink with a thermal resistance of 2.3°C/W or better.

ELECTRICAL CHARACTERISTICS

(See Figure 3 for Test Circuit).

Unless otherwise noted: V_{CC} = +220V, V_{BB} = +12V, C_L = 10 pF, T_C = 60°C.

DC Tests: $V_{IN} = +2.7V_{DC}$.

AC Tests: Output = $110V_{PP}$ (80V – 190V) at 1 MHz.

Symbol	Parameter	Conditions	LM2422			1114
			Min	Тур	Max	Units
I _{CC}	Supply Current	No Input Signal, No Video Input, No Output Load	36	45	54	mA
I_{BB}	Bias Current		18	27	36	mA
V _{OUT, 1}	DC Output Voltage	No AC Input Signal, V _{IN} = 2.7V _{DC}	124	129	134	V_{DC}
V _{OUT, 2}	DC Output Voltage	No AC Input Signal, V _{IN} = 1.2V _{DC}	200	205	210	V_{DC}
A _V	DC Voltage Gain	No AC Input Signal	-49	-52	-55	V/V
ΔA_V	Gain Matching	No AC Input Signal (1)		1.0		dB
LE	Linearity Error	No AC Input Signal (1)(2)		8		%
t _r	Rise Time, 80V to 190V	10% to 90% ⁽³⁾		12		ns
+OS	Overshoot			12		%
t _f	Fall Time, 80V to 190V	90% to 10% ⁽³⁾		12		ns
-OS	Overshoot	See ⁽³⁾		4		%
Ik _{ERROR}	Current Output Error	Output Current = 0 μA to 200 μA	-52	0	52	μΑ
Δlk_{ERROR}	Current Output Difference Between Channels	Output Current = 0 μA to 200 μA	0	NA	32	μΑ

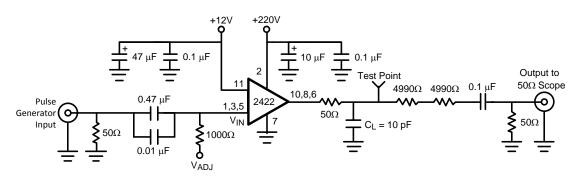
- (1) Calculated value from Voltage Gain test on each channel.
- (2) Linearity Error is the variation in DC gain from $V_{IN} = 1.15V$ to $V_{IN} = 4.35V$.

(3) Input from signal generator: t_r , $t_f < 1$ ns.

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AC TEST CIRCUIT



Note: 10 pF load includes parasitic capacitance.

Figure 3. Test Circuit (One Channel)

Figure 3 shows a typical test circuit for evaluation of the LM2422. This circuit is designed to allow testing of the LM2422 in a 50Ω environment without the use of an expensive FET probe. The two 4990Ω resistors form a 400:1 divider with the 50Ω resistor and the oscilloscope. A test point is included for easy use of an oscilloscope probe. The compensation capacitor is used to compensate the network to achieve flat frequency response.



TYPICAL PERFORMANCE CHARACTERISTICS

 $(V_{CC} = +220V_{DC}, V_{BB} = +12V_{DC}, C_L = 10 \text{ pF}, V_{OUT} = 110V_{PP} (80V - 190V), T_C = 60^{\circ}C, Test Circuit—Figure 3 unless otherwise specified)$

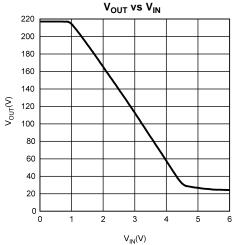


Figure 4.

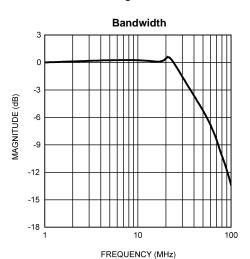
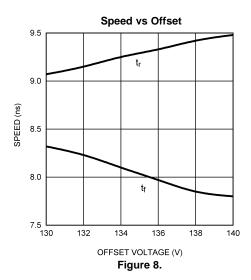
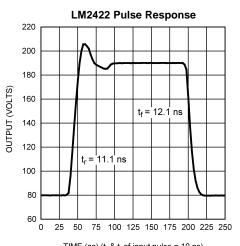
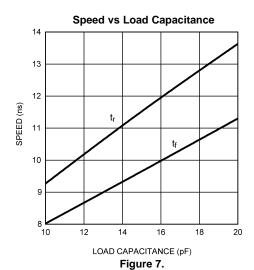


Figure 6.

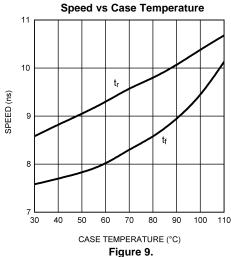




TIME (ns) ($t_r & t_f$ of input pulse = 10 ns) **Figure 5.**



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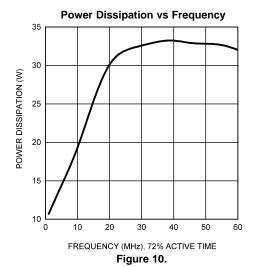


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STRUMENTS

TYPICAL PERFORMANCE CHARACTERISTICS

 $(V_{CC} = +220V_{DC}, V_{BB} = +12V_{DC}, C_L = 10 \text{ pF}, V_{OUT} = 110V_{PP} (80V - 190V), T_C = 60^{\circ}C, Test Circuit—Figure 3 unless otherwise specified)$



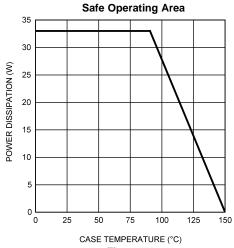


Figure 11.

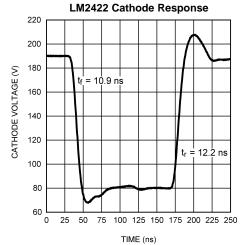


Figure 12.

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THEORY OF OPERATION

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The LM2422 is a high voltage monolithic three channel CRT driver suitable for DTV applications. The LM2422 operates with 220V and 12V power supplies. The part is housed in the industry standard 11-lead TO-220 molded plastic power package with thin leads for improved metal-to-metal spacing.

The circuit diagram of the LM2422 is shown in Figure 2. The PNP emitter follower, Q5, provides input buffering. Q1 and Q2 form a fixed gain cascode amplifier with resistors R1 and R2 setting the gain at -52. Emitter followers Q3 and Q4 isolate the high output impedance of the cascode stage from the capacitance of the CRT cathode. which decreases the sensitivity of the device to load capacitance. Q6 provides biasing to the output emitter follower stage to reduce crossover distortion at low signal levels.

Figure 3 shows a typical test circuit for evaluation of the LM2422. This circuit is designed to allow testing of the LM2422 in a 50 Ω environment without the use of an expensive FET probe. In this test circuit, the two 4.99 k Ω resistors form a 400:1 wideband, low capacitance probe when connected to a 50Ω coaxial cable and a 50Ω load (such as a 50Ω oscilloscope input). The input signal from the generator is ac coupled to the base of Q5.

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APPLICATION HINTS

INTRODUCTION

NSTRUMENTS

Texas Instruments is committed to provide application information that assists our customers in obtaining the best performance possible from our products. The following information is provided in order to support this commitment. The reader should be aware that the optimization of performance was done using a specific printed circuit board designed at Tl. Variations in performance can be realized due to physical changes in the printed circuit board and the application. Therefore, the designer should know that component value changes may be required in order to optimize performance in a given application. The values shown in this document can be used as a starting point for evaluation purposes. When working with high bandwidth circuits, good layout practices are also critical to achieving maximum performance.

IMPORTANT INFORMATION

The LM2422 performance is targeted for the HDTV market. The application circuits shown in this document to optimize performance and to protect against damage from CRT arc over are designed specifically for the LM2422. If another member of the LM242X family is used, please refer to its datasheet.

POWER SUPPLY BYPASS

Since the LM2422 is a wide bandwidth amplifier, proper power supply bypassing is critical for optimum performance. Improper power supply bypassing can result in large overshoot, ringing or oscillation. 0.1 μ F capacitors should be connected from the supply pins, V_{CC} and V_{BB} , to ground, as close to the LM2422 as is practical. Additionally, a 22 μ F or larger electrolytic capacitor should be connected from both supply pins to ground reasonably close to the LM2422.

ARC PROTECTION

During normal CRT operation, internal arcing may occasionally occur. This fast, high voltage, high-energy pulse can damage the LM2422 output stage. The application circuit shown in Figure 13 is designed to help clamp the voltage at the output of the LM2422 to a safe level. The clamp diodes, D1 and D2, should have a fast transient response, high peak current rating, low series impedance and low shunt capacitance. 1SS83 or equivalent diodes are recommended. D1 and D2 should have short, low impedance connections to V_{CC} and ground respectively. The cathode of D1 should be located very close to a separately decoupled bypass capacitor (C3 in Figure 13). The ground connection of D2 and the decoupling capacitor should be very close to the LM2422 ground. This will significantly reduce the high frequency voltage transients that the LM2422 would be subjected to during an arc over condition. Resistor R2 limits the arc over current that is seen by the diodes while R1 limits the current into the LM2422 as well as the voltage stress at the outputs of the device. R2 should be a $\frac{1}{2}$ W solid carbon type resistor. R1 can be a $\frac{1}{2}$ W metal or carbon film type resistor. Having large value resistors for R1 and R2 would be desirable, but this has the effect of increasing rise and fall times. Inductor L1 is critical to reduce the initial high frequency voltage levels that the LM2422 would be subjected to. The inductor will not only help protect the device but it will also help minimize rise and fall times as well as minimize EMI. For proper arc protection, it is important to not omit any of the arc protection components shown in Figure 13.

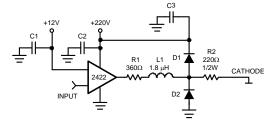


Figure 13. One Channel of the LM2422 with the Recommended Application Circuit



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EFFECT OF LOAD CAPACITANCE

Figure 7 shows the effect of increased load capacitance on the speed of the device. This demonstrates the importance of knowing the load capacitance in the application. Increasing the load capacitance from 10 pF to 20 pF adds about 4.5 ns to the rise time and 3.5 ns to the fall time. It is important to keep the board capacitance as low as possible to maximize the speed of the driver.

EFFECT OF OFFSET

Figure 8 shows the variation in rise and fall times when the output offset of the device is varied from 120V to $130V_{DC}$. Offset has little effect on the LM2422. The rise time increases less than 0.5 ns as the offset is increased in voltage and the fall time decreases by about 0.5 ns with the same offset adjustment.

THERMAL CONSIDERATIONS

Figure 9 shows the performance of the LM2422 in the test circuit shown in Figure 3 as a function of case temperature. The figure shows that the rise time of the LM2422 increases by about 2ns as the case temperature increases from 30°C to 110°C. Over the same case temperature range the fall time increased by about 2.5 ns.

Figure 10 shows the maximum power dissipation of the LM2422 vs. Frequency when all three channels of the device are driving into a 10 pF load with a $110V_{P-P}$ alternating one pixel on, one pixel off. Note that the frequency given in Figure 10 is half of the pixel frequency. The graph assumes a 72% active time (device operating at the specified frequency), which is typical in a TV application. The other 28% of the time the device is assumed to be sitting at the black level (190V in this case). A TV picture will not have frequency content over the whole picture exceeding 20 MHz. It is important to establish the worst case condition under normal viewing to give a realistic worst-case power dissipation for the LM2422. One test is a 1 to 30 MHz sine wave sweep over the active line. This would give a slightly lower power than taking the average of the power between 1 and 30 MHz. This average is 23.5 W. A sine wave will dissipate slightly less power, probably about 21 W or 22 W of power dissipation. All of this information is critical for the designer to establish the heat sink requirement for his application. The designer should note that if the load capacitance is increased the AC component of the total power dissipation will also increase.

The LM2422 case temperature must be maintained below 110°C given the maximum power dissipation estimate of 22W. If the maximum expected ambient temperature is 60°C and the maximum power dissipation is 22W then a maximum heat sink thermal resistance can be calculated:

$$R_{TH} = \frac{110^{\circ}\text{C} - 60^{\circ}\text{C}}{22\text{W}} = 2.3^{\circ}\text{C/W}$$
 (1)

This example assumes a capacitive load of 10 pF and no resistive load. The designer should note that if the load capacitance is increased the AC component of the total power dissipation will also increase.

OPTIMIZING TRANSIENT RESPONSE

Referring to Figure 13, there are three components (R1, R2 and L1) that can be adjusted to optimize the transient response of the application circuit. Increasing the values of R1 and R2 will slow the circuit down while decreasing overshoot. Increasing the value of L1 will speed up the circuit as well as increase overshoot. It is very important to use inductors with very high self-resonant frequencies, preferably above 300 MHz. Ferrite core inductors from J.W. Miller Magnetics (part # 78FR--K) were used for optimizing the performance of the device in the TI application board. The values shown in Figure 13 can be used as a good starting point for the evaluation of the LM2422. Using a variable resistor for R1 will simplify finding the value needed for optimum performance in a given application. Once the optimum value is determined the variable resistor can be replaced with a fixed value. Due to arc over considerations it is recommended that the values shown in Figure 13 not be changed by a large amount.

Figure 12 shows the typical cathode pulse response with an output swing of 110V_{PP} inside a modified production TV set using the LM1237 pre-amp.

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PC BOARD LAYOUT CONSIDERATIONS

For optimum performance, an adequate ground plane, isolation between channels, good supply bypassing and minimizing unwanted feedback are necessary. Also, the length of the signal traces from the signal inputs to the LM2422 and from the LM2422 to the CRT cathode should be as short as possible. The following references are recommended:

Ott, Henry W., "Noise Reduction Techniques in Electronic Systems", John Wiley & Sons, New York, 1976.

"Video Amplifier Design for Computer Monitors", TI Application Note 1013.

Pease, Robert A., "Troubleshooting Analog Circuits", Butterworth-Heinemann, 1991.

Because of its high small signal bandwidth, the part may oscillate in a TV if feedback occurs around the video channel through the chassis wiring. To prevent this, leads to the video amplifier input circuit should be shielded, and input circuit wiring should be spaced as far as possible from output circuit wiring.

TYPICAL APPLICATION

A typical application of the LM2422 is shown in Figure 14. Used in conjunction with a pre-amp with a 1.2V black level output no buffer transistors are required to obtain the correct black level at the cathodes. If the pre-amp has a black level closer to 2V, then an NPN transistor should be used to drop the video black level voltage closer to 1.2V.

The neck board in Figure 14 has two transistors in each channel enabling this board to work with pre-amps with a black level output as high as 2.5V. Some popular AVPs do have a black level of 2.5V. For lower black levels either one or both transistors would not be used.

It is important that the TV designer use component values for the driver output stage close to the values shown in Figure 14. These values have been selected to protect the LM2422 from arc over. Diodes D1–D6 must also be used for proper arc over protection. The TI demonstration board can be used to evaluate the LM2422 in a TV.

TI DEMONSTRATION BOARD

Figure 15 shows the routing and component placement on the TI LM2422 demonstration board. This board provides a good example of a layout that can be used as a guide for future layouts. Note the location of the following components:

- C4—V_{CC} bypass capacitor, located very close to pin 2 and ground pins
- C6—V_{BB} bypass capacitor, located close to pin 11 and ground
- C5, C8—V_{CC} bypass capacitors, near LM2422 and V_{CC} clamp diodes. Very important for arc protection.

The routing of the LM2422 outputs to the CRT is very critical to achieving optimum performance. Figure 16 shows the routing and component placement from pin 10 (V_{OUT1}) of the LM2422 to the blue cathode. Note that the components are placed so that they almost line up from the output pin of the LM2422 to the blue cathode pin of the CRT connector. This is done to minimize the length of the video path between these two components. Note also that D1, D2 and R3 are placed to minimize the size of the video nodes that they are attached to. This minimizes parasitic capacitance in the video path and also enhances the effectiveness of the protection diodes. The anode of protection diode D2 is connected directly to a section of the ground plane that has a short and direct path to the heater ground and the LM2422 ground pins. The cathode of D1 is connected to V_{CC} very close to decoupling capacitor C5 which is connected to the same area of the ground trace as D2. The diode placement and routing is very important for minimizing the voltage stress on the LM2422 during an arc over event.

This demonstration board uses large PCB holes to accommodate socket pins, which function to allow for multiple insertions of the LM2422 in a convenient manner. To benefit from the enhanced LM2422 package with thin leads, the device should be secured in small PCB holes to optimize the metal-to-metal spacing between the leads.

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CURRENT OUTPUT FOR IK FEEDBACK SYSTEMS

The LM2422 can be used in DTV applications that use an IK feedback system. Figure 14 shows an example of an interface circuit used to feed back the IK output of LM2422 to a preamplifier with an ac coupled IK input.

This feedback system consists of the preamp, LM2422, and interface circuit, forming a closed loop to automatically adjust the black level of the drive signals to the cutoff point of the RGB cathodes. Following is a description of the interface circuit operation.

The output at pin 9 of the LM2422 is filtered of high frequency noise by C14. D7 is used to limit the peak voltage at pin 9. Without this clamp diode the voltage would easily exceed 12V during active video, in which the cathode currents are much greater than the small currents being detected during vertical blanking. Exceeding 12V could damage Q1 and result in improper operation of the driver.

R35 is essential to convert the IK current to voltage. Choosing the value of R35 sets the gain of the feedback voltage, and consequently, the operating point of the tube. Once a stable operating point is established, this point can be fine-tuned using the adjustment range of the feedback system or standard preamp controls. Changing the value of R35 will change the cutoff voltage at the cathode. A smaller value of R35 requires more IK current to maintain the feedback loop. The cutoff voltage set at the cathode will be lower to adjust to the higher IK current. This additional current must come from the cathode; therefore, the cathode voltage is lower to meet higher current requirement. A higher value of R35 will do the opposite, raising the cathode voltage because less IK current is needed to maintain the same voltage at R35.

The emitter follower, Q1, isolates R35 from the input impedance of the preamp. R20 and R21 bias the emitter of Q1 to limit the maximum voltage to the preamp. These resistor values should be chosen to limit the maximum voltage at the emitter and protect the preamp from any large voltages that would otherwise occur during active video. C12 is used for further filtering of the IK signal. C9 is used to AC couple the IK signal to the preamp. The advantage of AC coupling is that any DC component (leakage current from the driver) of the IK signal is not detected by the IK sense input of the preamp.

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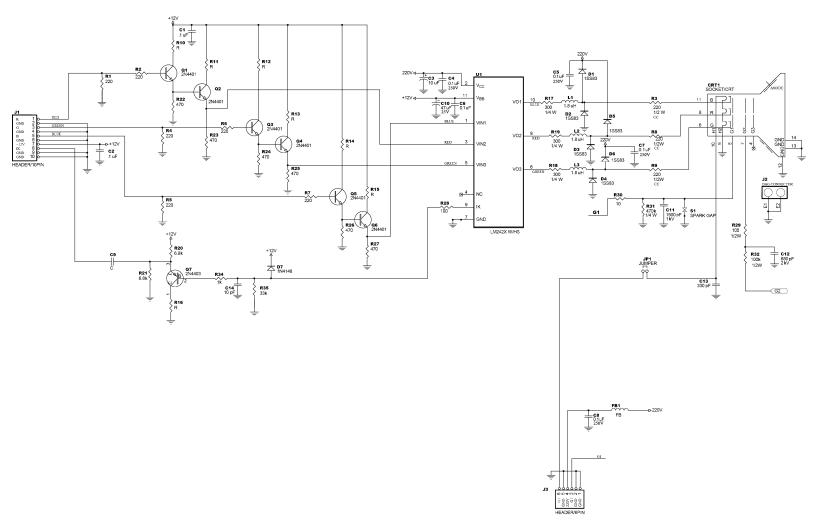


Figure 14. LM2422 DTV Applications Circuit

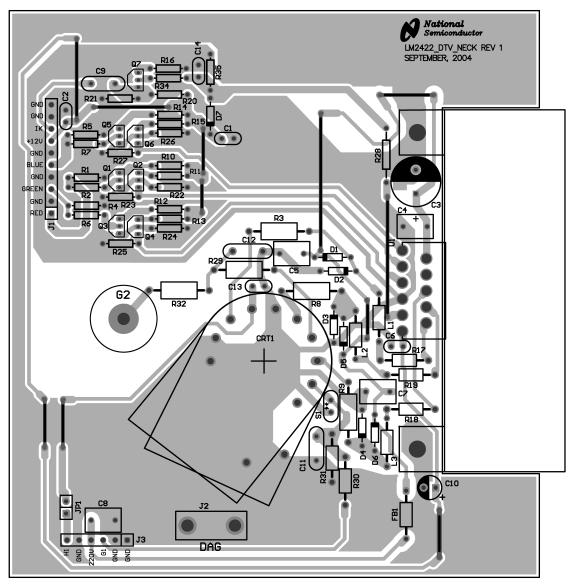


Figure 15. LM2422 DTV Demonstration Board Layout



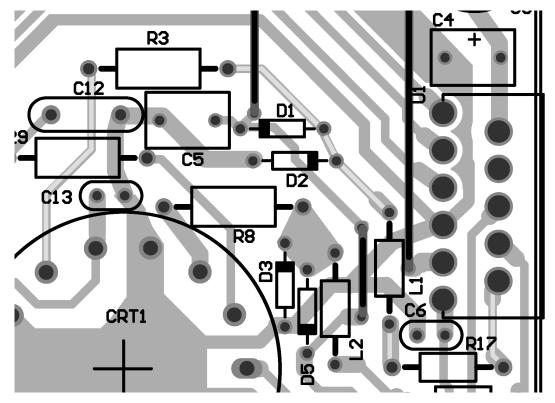


Figure 16. Trace Routing and Component Placement for Blue Channel Output

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REVISION HISTORY

Cł	Changes from Revision C (April 2013) to Revision D		
•	Changed layout of National Data Sheet to TI format		13

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